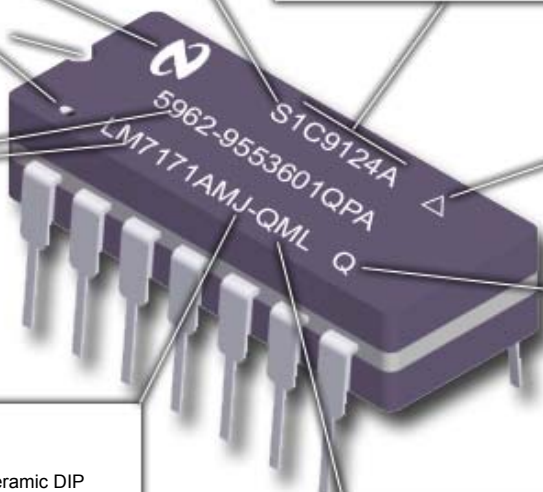


Top Mark Information for Hi-Rel Products



Plant of Manufacture Code for Military Products

| Country | Code |
|---------------------|------|
| Philippines – TEAM | A |
| Philippines – Amkor | H |
| Malacca | M |
| Singapore | S |
| South Portland | Z |
| USA Subs | X |

883 & 38535 Date Code

2nd Digit: Last digit of year wafer sort was performed

3rd Digit: Alpha character indicating calendar quarter in which wafer sort was performed

| Character | Months | Weeks |
|-----------|---------------|---------|
| A | Jan – Mar | 1 - 13 |
| B | Apr – Jun | 14 - 26 |
| C | Jul – Sep | 27 - 39 |
| D | Oct – Dec | 40 - 53 |
| GF | Prior to 1988 | |

4th & 5th Digits: Calendar Year

6th & 7th Digits: Seal Week

8th Digit: Alpha character indicating the lot is a sub-lot (when applicable)

Products available to DSCC drawings may be dual marked

Military Electrostatic Discharge (ESD) Sensitivity Indicator

| Mark | Class | Voltage |
|------|-------|--------------|
| △ | 1 | 0-1999V |
| △△ | 2 | 2000 – 3999V |
| -- | 3 | ≥ 4000V |

QML Certification Mark

IC Package Types

| | |
|--------|---|
| D | Multi-layer Ceramic DIP |
| E | Ceramic LCC |
| F | Glass / Metal Flatpak |
| H | Multi-Lead CAN |
| J | Ceramic DIP |
| J-8 | 8-lead Ceramic DIP (Frit-Seal Mini-Dip package) |
| K | TO-3 CAN in Steel |
| KSteel | TO-3 CAN in Steel |
| U | Pin Grid Array |
| W | Ceramic Flatpak |
| WG | Ceramic Gullwing Flatpak |

Part Number Device Suffix

| | |
|-------|--------------------------|
| /883 | Compliant to MIL-STD-883 |
| QB | MIL-STD-883* |
| -QML | QML |
| -QMLV | Space Level QML |
| -QV | Space Level QML |
| -MLS | Non QML Space Level |
| -MIL | Non Compliant B Level |

* Some products using the QB designator may not be compliant to MIL-STD-883. Contact NSC Sales Office for details.

Note1: Not all marks shown may appear on all products

Note 2: Format of mark layout may vary from package to package